





an Open Access Journal by MDPI

# **Smart Manufacturing and Industry 4.0, 2nd Edition**

Guest Editors:

### Dr. Marcos de Sales Guerra Tsuzuki

Department of Mechatronics and Mechanical Systems Engineering, Universidade de São Paulo, São Paulo 2231, Brazil

#### Dr. Ahmad Barari

Department of Automotive, Mechanical and Manufacturing Engineering, Faculty of Engineering and Applied Science, University of Ontario Institute of Technology, Oshawa, ON L1H 7K4. Canada

Deadline for manuscript submissions:

30 September 2024

## **Message from the Guest Editors**

Smart manufacturing processes and systems have been receiving a great amount of attention through the latest innovations, ongoing efforts, and best practices in the Industry 4.0 era. The idea of the smart factory and its cyber systems, intelligent support systems for manufacturing decision making, intelligent inspection to monitor production health, in situ data collection and fusion of sensor information for manufacturing processes, collaborative robots, self-configuration and self-diagnosis, Internet of Things for manufacturing shop floors, intelligent prescriptive and preventive maintenance, simulationassisted process control and digital twins, big data analytics for manufacturing systems and processes, ondemand and customized processes utilizing the hybrid model of additive and subtractive manufacturing, autonomy and autonomous vehicles, smart quality assurance and intelligent inspection, data-driven and model-based prognostics, and zero defect production are among the most important topics that need further research attention.











an Open Access Journal by MDPI

### **Editor-in-Chief**

# **Prof. Dr. Giulio Nicola Cerullo**Dipartimento di Fisica, Politecnico di Milano, Piazza L. da Vinci 32, 20133 Milano, Italy

## **Message from the Editor-in-Chief**

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

### **Author Benefits**

**Open Access:** free for readers, with article processing charges (APC) paid by authors or their institutions.

**High Visibility:** indexed within Scopus, SCIE (Web of Science), Inspec, CAPlus / SciFinder, and other databases.

**Journal Rank:** JCR - Q2 (*Engineering, Multidisciplinary*) / CiteScore - Q1 (*General Engineering*)

#### **Contact Us**